

T-1 3/4 (5mm) BI-LEVEL LED INDICATOR

Part Number: WP1503EB/2SRD

Super Bright Red

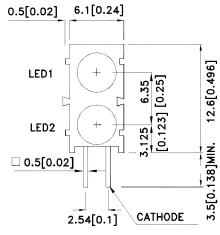
Features

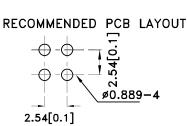
- Pre-trimmed leads for pc board mounting.
- Stackable units.
- Colors can be mixed in a single housing.
- Black case enhances contrast ratio.
- Wide viewing angle.
- High reliability life measured in years.
- Housing UL rating:94V-0.
- Housing material: type 66 nylon.
- · RoHS compliant.

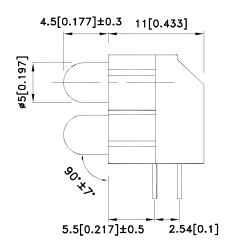
Description

The Super Bright Red source color devices are made with Gallium Aluminum Arsenide Red Light Emitting Diode.

Package Dimensions







- 1. All dimensions are in millimeters (inches)
- 2. Tolerance is ±0.25(0.01") unless otherwise noted
- Lead spacing is measured where the leads emerge from the package.
 The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice.

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Selection Guide

| Part No. Dice | | Lens Type | | lv (mcd) [2] @ 20mA | |
|---------------|---------------------------|--------------|------|------------------------|-------|
| | | 7,1 | Min. | Тур. | 201/2 |
| WP1503EB/2SRD | Super Bright Red (GaAlAs) | Red Diffused | 500 | 1000 | 60° |

- 1. θ 1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.
- 2. Luminous intensity/ luminous Flux: +/-15%.

Electrical / Optical Characteristics at TA=25°C

| Symbol | Parameter | Device | Тур. | Max. | Units | Test Conditions |
|--------|--------------------------|------------------|------|------|-------|---------------------------|
| λpeak | Peak Wavelength | Super Bright Red | 660 | | nm | IF=20mA |
| λD [1] | Dominant Wavelength | Super Bright Red | 640 | | nm | IF=20mA |
| Δλ1/2 | Spectral Line Half-width | Super Bright Red | 20 | | nm | IF=20mA |
| С | Capacitance | Super Bright Red | 45 | | pF | V _F =0V;f=1MHz |
| VF [2] | Forward Voltage | Super Bright Red | 1.85 | 2.5 | V | IF=20mA |
| lr | Reverse Current | Super Bright Red | | 10 | uA | VR = 5V |

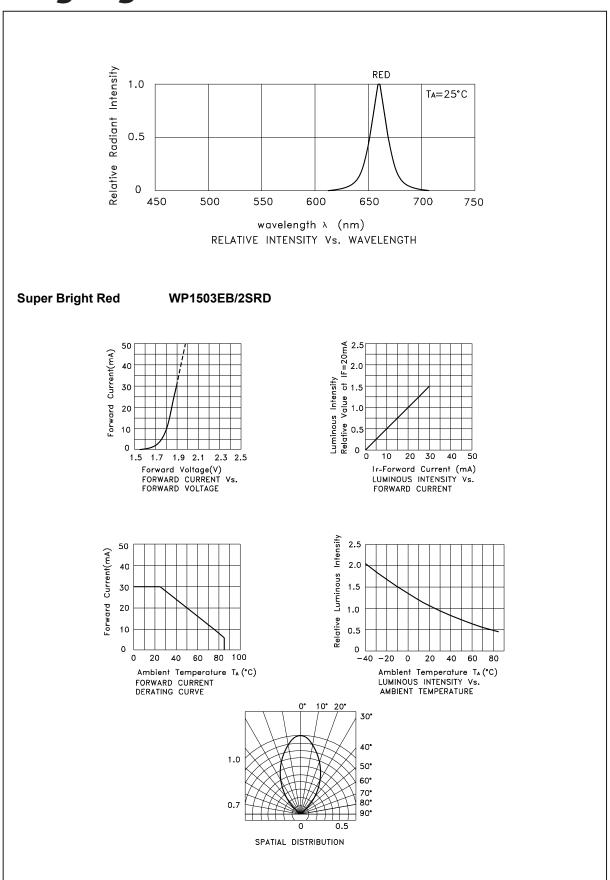
- 1.Wavelength: +/-1nm. 2. Forward Voltage: +/-0.1V.

Absolute Maximum Ratings at TA=25°C

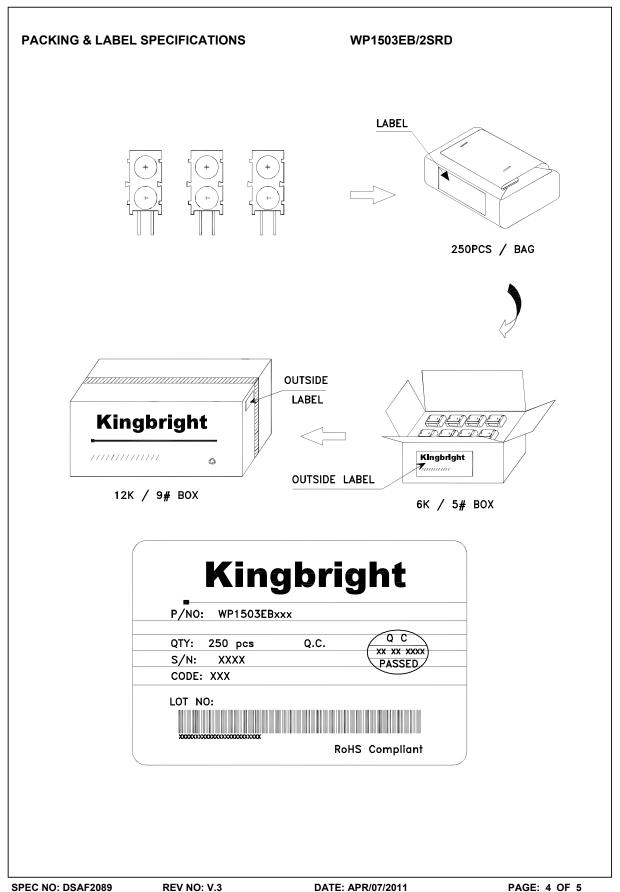
| Parameter | Super Bright Red | Units | |
|-------------------------------|---------------------|-------|--|
| Power dissipation | 75 | mW | |
| DC Forward Current | 30 | mA | |
| Peak Forward Current [1] | 155 | mA | |
| Reverse Voltage | 5 | V | |
| Operating/Storage Temperature | -40°C To +85°C | | |
| Lead Solder Temperature [2] | 260°C For 3 Seconds | | |
| Lead Solder Temperature [3] | 260°C For 5 Seconds | | |

- 1. 1/10 Duty Cycle, 0.1ms Pulse Width.
- 2. 2mm below package base.
 3. 5mm below package base.

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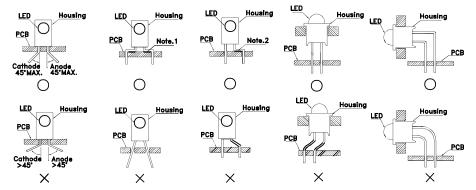


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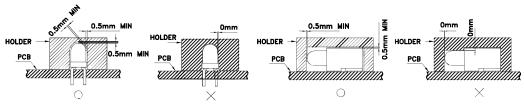
PRECAUTIONS

 The lead pitch of the LED must match the pitch of the mounting holes on the PCB during component placement. Lead—forming may be required to insure the lead pitch matches the hole pitch. Refer to the figure below for proper lead forming procedures.

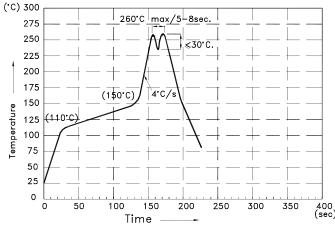


" \bigcirc " Correct mounting method "imes" Incorrect mounting method

2. During soldering, component covers and holders should leave clearance to avoid placing damaging stress on the LED during soldering.



- 3. The tip of the soldering iron should never touch the lens epoxy.
- 4. Through—hole LEDs are incompatible with reflow soldering.
- 5. If the LED will undergo multiple soldering passes or face other processes where the part may be subjected to intense heat, please check with Kingbright for compatibility.
- 6. Recommended Wave Soldering Profile for Kingbright Thru-Hole Products



NOTES:

- 1.Recommend the wave temperature 245°C~260°C.The maximum soldering temperature should be less than 260°C.
- 2.Do not apply stress on epoxy resins when temperature is over 85°C.
- 3. The soldering profile apply to the lead free soldering (Sn/Cu/Ag alloy).
- 4.During wave soldering, the PCB top-surface temperature should be kept below 105°C.
- 5.No more than once.

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